Welcome to E-XFL.COM

Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	35
Number of Macrocells	560
Number of Gates	12000
Number of I/O	153
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	208-BFQFP Exposed Pad
Supplier Device Package	208-RQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm9560arc208-10

General Description

The MAX 9000 family of in-system-programmable, high-density, high-performance EPLDs is based on Altera's third-generation MAX architecture. Fabricated on an advanced CMOS technology, the EEPROM-based MAX 9000 family provides 6,000 to 12,000 usable gates, pin-to-pin delays as fast as 10 ns, and counter speeds of up to 144 MHz. The -10 speed grade of the MAX 9000 family is compliant with the ***PCI Local Bus Specification, Revision 2.2***. Table 3 shows the speed grades available for MAX 9000 devices.

Table 3. MAX 9000 Speed Grade Availability

Device	Speed Grade		
	-10	-15	-20
EPM9320		✓	✓
EPM9320A	✓		
EPM9400		✓	✓
EPM9480		✓	✓
EPM9560		✓	✓
EPM9560A	✓		

Table 4 shows the performance of MAX 9000 devices for typical functions.

Table 4. MAX 9000 Performance *Note (1)*

Application	Macrocells Used	Speed Grade			Units
		-10	-15	-20	
16-bit loadable counter	16	144	118	100	MHz
16-bit up/down counter	16	144	118	100	MHz
16-bit prescaled counter	16	144	118	100	MHz
16-bit address decode	1	5.6 (10)	7.9 (15)	10 (20)	ns
16-to-1 multiplexer	1	7.7 (12.1)	10.9 (18)	16 (26)	ns

Note:

(1) Internal logic array block (LAB) performance is shown. Numbers in parentheses show external delays from row input pin to row I/O pin.

The MAX 9000 architecture supports high-density integration of system-level logic functions. It easily integrates multiple programmable logic devices ranging from PALs, GALs, and 22V10s to field-programmable gate array (FPGA) devices and EPLDs.

All MAX 9000 device packages provide four dedicated inputs for global control signals with large fan-outs. Each I/O pin has an associated I/O cell register with a clock enable control on the periphery of the device. As outputs, these registers provide fast clock-to-output times; as inputs, they offer quick setup times.

MAX 9000 EPLDs provide 5.0-V in-system programmability (ISP). This feature allows the devices to be programmed and reprogrammed on the printed circuit board (PCB) for quick and efficient iterations during design development and debug cycles. MAX 9000 devices are guaranteed for 100 program and erase cycles.

MAX 9000 EPLDs contain 320 to 560 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND / fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. For increased flexibility, each macrocell offers a dual-output structure that allows the register and the product terms to be used independently. This feature allows register-rich and combinatorial-intensive designs to be implemented efficiently. The dual-output structure of the MAX 9000 macrocell also improves logic utilization, thus increasing the effective capacity of the devices. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 9000 family provides programmable speed / power optimization. Speed-critical portions of a design can run at high speed / full power, while the remaining portions run at reduced speed / low power. This speed / power optimization feature enables the user to configure one or more macrocells to operate at 50% or less power while adding only a nominal timing delay. MAX 9000 devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. MAX 9000 devices offer the MultiVolt feature, which allows output drivers to be set for either 3.3-V or 5.0-V operation in mixed-voltage systems.

The MAX 9000 family is supported by Altera's MAX+PLUS II development system, a single, integrated software package that offers schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The MAX+PLUS II software provides EDIF 2 0 0 and 3 0 0, LPM, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The MAX+PLUS II software runs on Windows-based PCs as well as Sun SPARCstation, HP 9000 Series 700/800, and IBM RISC System/6000 workstations.

For more information on development tools, see the *MAX+PLUS II Programmable Logic Development System & Software Data Sheet*.

Functional Description

MAX 9000 devices use a third-generation MAX architecture that yields both high performance and a high degree of utilization for most applications. The MAX 9000 architecture includes the following elements:

- Logic array blocks
- Macrocells
- Expander product terms (shareable and parallel)
- FastTrack Interconnect
- Dedicated inputs
- I/O cells

Figure 1 shows a block diagram of the MAX 9000 architecture.

The MAX+PLUS II Compiler automatically allocates as many as three sets of up to five parallel expanders to macrocells that require additional product terms. Each set of expanders incurs a small, incremental timing delay (t_{PEXP}). For example, if a macrocell requires 14 product terms, the Compiler uses the five dedicated product terms within the macrocell and allocates two sets of parallel expanders; the first set includes five product terms and the second set includes four product terms, increasing the total delay by $2 \times t_{PEXP}$.

Two groups of eight macrocells within each LAB (e.g., macrocells 1 through 8 and 9 through 16) form two chains to lend or borrow parallel expanders. A macrocell borrows parallel expanders from lower-numbered macrocells. For example, macrocell 8 can borrow parallel expanders from macrocell 7, from macrocells 7 and 6, or from macrocells 7, 6, and 5. Within each group of 8, the lowest-numbered macrocell can only lend parallel expanders and the highest-numbered macrocell can only borrow them.

FastTrack Interconnect

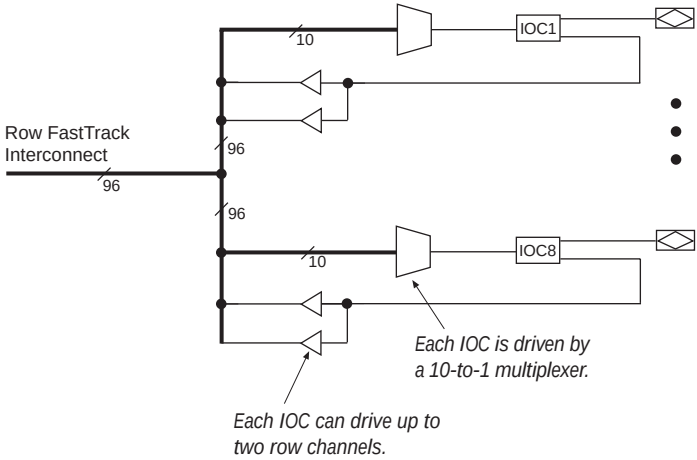
In the MAX 9000 architecture, connections between macrocells and device I/O pins are provided by the FastTrack Interconnect, a series of continuous horizontal and vertical routing channels that traverse the entire device. This device-wide routing structure provides predictable performance even in complex designs. In contrast, the segmented routing in FPGAs requires switch matrices to connect a variable number of routing paths, increasing the delays between logic resources and reducing performance. Figure 6 shows the interconnection of four adjacent LABs with row and column interconnects.

A row interconnect channel can be fed by the output of the macrocell through a 4-to-1 multiplexer that the macrocell shares with three column channels. If the multiplexer is used for a macrocell-to-row connection, the three column signals can access another row channel via an additional 3-to-1 multiplexer. Within any LAB, the multiplexers provide all 48 column channels with access to 32 row channels.

Row-to-I/O Cell Connections

Figure 8 illustrates the connections between row interconnect channels and IOCs. An input signal from an IOC can drive two separate row channels. When an IOC is used as an output, the signal is driven by a 10-to-1 multiplexer that selects the row channels. Each end of the row channel feeds up to eight IOCs on the periphery of the device.

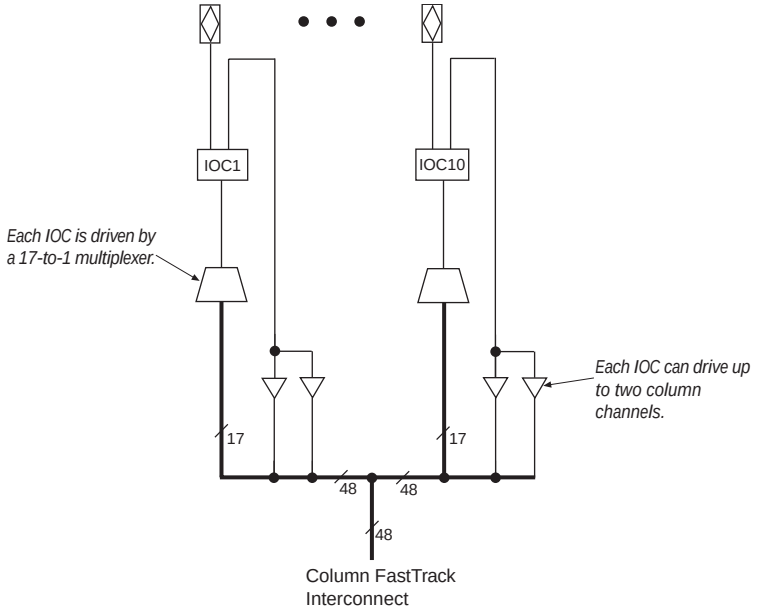
Figure 8. MAX 9000 Row-to-IOC Connections



Column-to-I/O Cell Connections

Each end of a column channel has up to 10 IOCs (see Figure 9). An input signal from an IOC can drive two separate column channels. When an IOC is used as an output, the signal is driven by a 17-to-1 multiplexer that selects the column channels.

Figure 9. MAX 9000 Column-to-IOC Connections



Dedicated Inputs

In addition to the general-purpose I/O pins, MAX 9000 devices have four dedicated input pins. These dedicated inputs provide low-skew, device-wide signal distribution to the LABs and IOCs in the device, and are typically used for global clock, clear, and output enable control signals. The global control signals can feed the macrocell or IOC clock and clear inputs, as well as the IOC output enable. The dedicated inputs can also be used as general-purpose data inputs because they can feed the row FastTrack Interconnect (see Figure 2 on page 7).

I/O Cells

Figure 10 shows the IOC block diagram. Signals enter the MAX 9000 device from either the I/O pins that provide general-purpose input capability or from the four dedicated inputs. The IOCs are located at the ends of the row and column interconnect channels.

The output buffer in each IOC has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A slower slew rate reduces board-level noise and adds a nominal timing delay to the output buffer delay (t_{OD}) parameter. The fast slew rate should be used for speed-critical outputs in systems that are adequately protected against noise. Designers can specify the slew rate on a pin-by-pin basis during design entry or assign a default slew rate to all pins on a global basis. The slew rate control affects both rising and falling edges of the output signals.

Table 6. Peripheral Bus Sources

Peripheral Control Signal	Source			
	EPM9320 EPM9320A	EPM9400	EPM9480	EPM9560 EPM9560A
OE0/ENA0	Row C	Row E	Row F	Row G
OE1/ENA1	Row B	Row E	Row F	Row F
OE2/ENA2	Row A	Row E	Row E	Row E
OE3/ENA3	Row B	Row B	Row B	Row B
OE4/ENA4	Row A	Row A	Row A	Row A
OE5	Row D	Row D	Row D	Row D
OE6	Row C	Row C	Row C	Row C
OE7/CLR1	Row B/GOE	Row B/GOE	Row B/GOE	Row B/GOE
CLR0/ENA5	Row A/GCLR	Row A/GCLR	Row A/GCLR	Row A/GCLR
CLK0	GCLK1	GCLK1	GCLK1	GCLK1
CLK1	GCLK2	GCLK2	GCLK2	GCLK2
CLK2	Row D	Row D	Row D	Row D
CLK3	Row C	Row C	Row C	Row C

Output Configuration

The MAX 9000 device architecture supports the MultiVolt I/O interface feature, which allows MAX 9000 devices to interface with systems of differing supply voltages. The 5.0-V devices in all packages can be set for 3.3-V or 5.0-V I/O pin operation. These devices have one set of V_{CC} pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The VCCINT pins must always be connected to a 5.0-V power supply. With a 5.0-V V_{CCINT} level, input voltages are at TTL levels and are therefore compatible with 3.3-V and 5.0-V inputs.

The VCCIO pins can be connected to either a 3.3-V or 5.0-V power supply, depending on the output requirements. When the VCCIO pins are connected to a 5.0-V power supply, the output levels are compatible with 5.0-V systems. When the VCCIO pins are connected to a 3.3-V power supply, the output high is at 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with V_{CCIO} levels lower than 4.75 V incur a nominally greater timing delay of t_{OD2} instead of t_{OD1}.

In-System Programmability (ISP)

MAX 9000 devices can be programmed in-system through a 4-pin JTAG interface. ISP offers quick and efficient iterations during design development and debug cycles. The MAX 9000 architecture internally generates the 12.0-V programming voltage required to program EEPROM cells, eliminating the need for an external 12.0-V power supply to program the devices on the board. During ISP, the I/O pins are tri-stated to eliminate board conflicts.

ISP simplifies the manufacturing flow by allowing the devices to be mounted on a printed circuit board with standard pick-and-place equipment before they are programmed. MAX 9000 devices can be programmed by downloading the information via in-circuit testers, embedded processors, or the Altera BitBlaster, ByteBlaster, or ByteBlasterMV download cable. (The ByteBlaster cable is obsolete and has been replaced by the ByteBlasterMV cable, which can interface with 2.5-V, 3.3-V, and 5.0-V devices.) Programming the devices after they are placed on the board eliminates lead damage on high pin-count packages (e.g., QFP packages) due to device handling. MAX 9000 devices can also be reprogrammed in the field (i.e., product upgrades can be performed in the field via software or modem).

In-system programming can be accomplished with either an adaptive or constant algorithm. An adaptive algorithm reads information from the unit and adapts subsequent programming steps to achieve the fastest possible programming time for that unit. Because some in-circuit testers platforms have difficulties supporting an adaptive algorithm, Altera offers devices tested with a constant algorithm. Devices tested to the constant algorithm have an “F” suffix in the ordering code.

Programming Sequence

During in-system programming, instructions, addresses, and data are shifted into the MAX 9000 device through the TDI input pin. Data is shifted out through the TDO output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

1. *Enter ISP.* The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.

2. *Check ID.* Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.

3. *Bulk Erase.* Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.

4. *Program.* Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.

5. *Verify.* Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.

6. *Exit ISP.* An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

Programming a Single MAX 9000 Device

The time required to program a single MAX 9000 device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$

where: t_{PROG} = Programming time
t_{PPULSE} = Sum of the fixed times to erase, program, and verify the EEPROM cells
$Cycle_{PTCK}$ = Number of TCK cycles to program a device
f_{TCK} = TCK frequency

The ISP times for a stand-alone verification of a single MAX 9000 device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$

where: t_{VER} = Verify time
t_{VPULSE} = Sum of the fixed times to verify the EEPROM cells
$Cycle_{VTCK}$ = Number of TCK cycles to verify a device

The programming times described in Tables 7 through 9 are associated with the worst-case method using the ISP algorithm.

Table 7. MAX 9000 t_{PULSE} & $Cycle_{TCK}$ Values

Device	Programming		Stand-Alone Verification	
	t_{PPULSE} (s)	$Cycle_{PTCK}$	t_{VPULSE} (s)	$Cycle_{VTCK}$
EPM9320 EPM9320A	11.79	2,966,000	0.15	1,806,000
EPM9400	12.00	3,365,000	0.15	2,090,000
EPM9480	12.21	3,764,000	0.15	2,374,000
EPM9560 EPM9560A	12.42	4,164,000	0.15	2,658,000

Tables 8 and 9 show the in-system programming and stand alone verification times for several common test clock frequencies.

Table 8. MAX 9000 In-System Programming Times for Different Test Clock Frequencies

Device	f_{TCK}								Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM9320 EPM9320A	12.09	12.38	13.27	14.76	17.72	26.62	41.45	71.11	s
EPM9400	12.34	12.67	13.68	15.37	18.73	28.83	45.65	79.30	s
EPM9480	12.59	12.96	14.09	15.98	19.74	31.03	49.85	87.49	s
EPM9560 EPM9560A	12.84	13.26	14.50	16.59	20.75	33.24	54.06	95.70	s

Table 9. MAX 9000 Stand-Alone Verification Times for Different Test Clock Frequencies

Device	f_{TCK}								Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM9320 EPM9320A	0.33	0.52	1.06	1.96	3.77	9.18	18.21	36.27	s
EPM9400	0.36	0.57	1.20	2.24	4.33	10.60	21.05	41.95	s
EPM9480	0.39	0.63	1.34	2.53	4.90	12.02	23.89	47.63	s
EPM9560 EPM9560A	0.42	0.69	1.48	2.81	5.47	13.44	26.73	53.31	s

Programming with External Hardware

MAX 9000 devices can be programmed on Windows-based PCs with an Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs continuity checking to ensure adequate electrical contact between the adapter and the device.

For more information, see the *Altera Programming Hardware Data Sheet*.

The MAX+PLUS II software can use text- or waveform-format test vectors created with the MAX+PLUS II Text Editor or Waveform Editor to test a programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 9000 device with the results of simulation.

Data I/O, BP Microsystems, and other programming hardware manufacturers also provide programming support for Altera devices.

For more information, see *Programming Hardware Manufacturers.*

IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

MAX 9000 devices support JTAG BST circuitry as specified by IEEE Std. 1149.1-1990. Table 10 describes the JTAG instructions supported by the MAX 9000 family. The pin-out tables starting on page 38 show the location of the JTAG control pins for each device. If the JTAG interface is not required, the JTAG pins are available as user I/O pins.

Table 10. MAX 9000 JTAG Instructions

JTAG Instruction	Description
SAMPLE/PRELOAD	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins.
EXTEST	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS	Places the 1-bit bypass register between the `TDI` and `TDO` pins, which allows the BST data to pass synchronously through a selected device to adjacent devices during normal device operation.
IDCODE	Selects the IDCODE register and places it between `TDI` and `TDO`, allowing the IDCODE to be shifted out of `TDO`. Supported by the EPM9320A, EPM9400, EPM9480, and EPM9560A devices only.
UESCODE	Selects the user electronic signature (UESCODE) register and allows the UESCODE to be shifted out of `TDO` serially. This instruction is supported by MAX 9000A devices only.
ISP Instructions	These instructions are used when programming MAX 9000 devices via the JTAG ports with the BitBlaster or ByteBlasterMV download cable, or using a Jam File (**.jam**), Jam Byte-Code File (**.jbc**), or Serial Vector Format (**.svf**) File via an embedded processor or test equipment.

The instruction register length for MAX 9000 devices is 10 bits. EPM9320A and EPM9560A devices support a 16-bit UESCODE register. Tables 11 and 12 show the boundary-scan register length and device IDCODE information for MAX 9000 devices.

Table 11. MAX 9000 Boundary-Scan Register Length

Device	Boundary-Scan Register Length
EPM9320, EPM9320A	504
EPM9400	552
EPM9480	600
EPM9560, EPM9560A	648

Table 12. 32-Bit MAX 9000 Device IDCODE *Note (1)*

Device	IDCODE (32 Bits)			
	Version (4 Bits)	Part Number (16 Bits) *(2)*	Manufacturer's Identity (11 Bits)	1 (1 Bit)
EPM9320A *(3)*	0000	1001 0011 0010 0000	00001101110	1
EPM9400	0000	1001 0100 0000 0000	00001101110	1
EPM9480	0000	1001 0100 1000 0000	00001101110	1
EPM9560A *(3)*	0000	1001 0101 0110 0000	00001101110	1

Notes:

(1) The IDCODE's least significant bit (LSB) is always 1.
(2) The most significant bit (MSB) is on the left.
(3) Although the EPM9320A and EPM9560A devices support the IDCODE instruction, the EPM9320 and EPM9560 devices do not.

Figure 11 shows the timing requirements for the JTAG signals.

Figure 11. MAX 9000 JTAG Waveforms

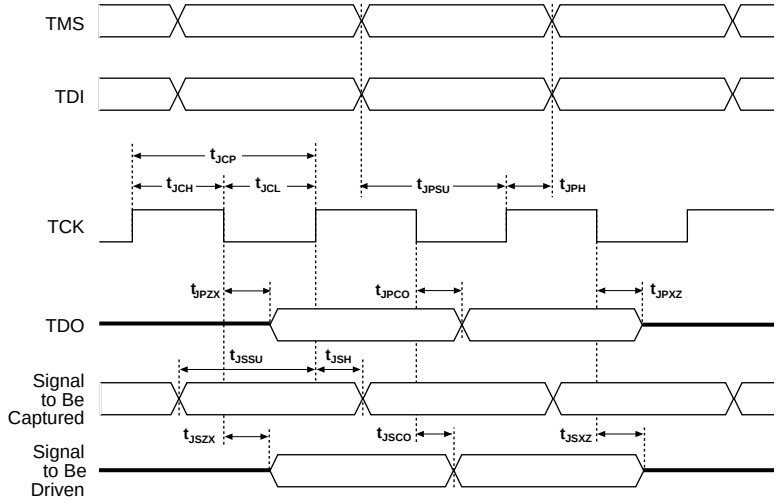


Table 13 shows the JTAG timing parameters and values for MAX 9000 devices.

Table 13. JTAG Timing Parameters & Values for MAX 9000 Devices

Symbol	Parameter	Min	Max	Unit
t_{JCP}	TCK clock period	100		ns
t_{JCH}	TCK clock high time	50		ns
t_{JCL}	TCK clock low time	50		ns
t_{JPSU}	JTAG port setup time	20		ns
t_{JPH}	JTAG port hold time	45		ns
t_{JPCO}	JTAG port clock to output		25	ns
t_{JPZX}	JTAG port high impedance to valid output		25	ns
t_{JPXZ}	JTAG port valid output to high impedance		25	ns
t_{JSSU}	Capture register setup time	20		ns
t_{JSH}	Capture register hold time	45		ns
t_{JSCO}	Update register clock to output		25	ns
t_{JSZX}	Update register high impedance to valid output		25	ns
t_{JSXZ}	Update register valid output to high impedance		25	ns

For detailed information on JTAG operation in MAX 9000 devices, refer to *Application Note 39 (IEEE 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices)*.

Operating Conditions

Tables 14 through 20 provide information on absolute maximum ratings, recommended operating conditions, operating conditions, and capacitance for MAX 9000 devices.

Table 14. MAX 9000 Device Absolute Maximum Ratings *Note (1)*

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply voltage	With respect to ground *(2)*	–2.0	7.0	V
V_I	DC input voltage		–2.0	7.0	V
V_{CCISP}	Supply voltage during in-system programming		–2.0	7.0	V
I_{OUT}	DC output current, per pin		–25	25	mA
T_{STG}	Storage temperature	No bias	–65	150	° C
T_{AMB}	Ambient temperature	Under bias	–65	135	° C
T_J	Junction temperature	Ceramic packages, under bias		150	° C
		PQFP and RQFP packages, under bias		135	° C

Table 15. MAX 9000 Device Recommended Operating Conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CCINT}	Supply voltage for internal logic and input buffers	*(3)*, *(4)*	4.75 (4.50)	5.25 (5.50)	V
V_{CCIO}	Supply voltage for output drivers, 5.0-V operation	*(3)*, *(4)*	4.75 (4.50)	5.25 (5.50)	V
	Supply voltage for output drivers, 3.3-V operation	*(3)*, *(4)*	3.00 (3.00)	3.60 (3.60)	V
V_{CCISP}	Supply voltage during in-system programming		4.75	5.25	V
V_I	Input voltage		–0.5	V_{CCINT} + 0.5	V
V_O	Output voltage		0	V_{CCIO}	V
T_A	Ambient temperature	For commercial use	0	70	° C
		For industrial use	–40	85	° C
T_J	Junction temperature	For commercial use	0	90	° C
		For industrial use	–40	105	° C
t_R	Input rise time			40	ns
t_F	Input fall time			40	ns

Table 22. MAX 9000 Internal Timing Characteristics *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-10		-15		-20		
			Min	Max	Min	Max	Min	Max	
t_{LAD}	Logic array delay			3.5		4.0		4.5	ns
t_{LAC}	Logic control array delay			3.5		4.0		4.5	ns
t_{IC}	Array clock delay			3.5		4.0		4.5	ns
t_{EN}	Register enable time			3.5		4.0		4.5	ns
t_{SEXP}	Shared expander delay			3.5		5.0		7.5	ns
t_{PEXP}	Parallel expander delay			0.5		1.0		2.0	ns
t_{RD}	Register delay			0.5		1.0		1.0	ns
t_{COMB}	Combinatorial delay			0.4		1.0		1.0	ns
t_{SU}	Register setup time		2.4		3.0		4.0		ns
t_{H}	Register hold time		2.0		3.5		4.5		ns
t_{PRE}	Register preset time			3.5		4.0		4.5	ns
t_{CLR}	Register clear time			3.7		4.0		4.5	ns
t_{FTD}	FastTrack drive delay			0.5		1.0		2.0	ns
t_{LPA}	Low-power adder	*(5)*		10.0		15.0		20.0	ns

Table 24. Interconnect Delays

Symbol	Parameter	Conditions	Speed Grade						Unit
			-10		-15		-20		
			Min	Max	Min	Max	Min	Max	
t_{LOCAL}	LAB local array delay			0.5		0.5		0.5	ns
t_{ROW}	FastTrack row delay	*(6)*		0.9		1.4		2.0	ns
t_{COL}	FastTrack column delay	*(6)*		0.9		1.7		3.0	ns
t_{DIN_D}	Dedicated input data delay			4.0		4.5		5.0	ns
t_{DIN_CLK}	Dedicated input clock delay			2.7		3.5		4.0	ns
t_{DIN_CLR}	Dedicated input clear delay			4.5		5.0		5.5	ns
t_{DIN_IOC}	Dedicated input I/O register clock delay			2.5		3.5		4.5	ns
t_{DIN_IO}	Dedicated input I/O register control delay			5.5		6.0		6.5	ns

Notes to tables:

(1) These values are specified under the MAX 9000 device recommended operating conditions, shown in Table 15 on page 27.

(2) See *Application Note 77 (Understanding MAX 9000 Timing)* for more information on test conditions for $\mathbf{t_{PD1}}$ and $\mathbf{t_{PD2}}$ delays.

(3) This parameter is a guideline that is sample-tested only. It is based on extensive device characterization. This parameter applies for both global and array clocking as well as both macrocell and I/O cell registers.

(4) Measured with a 16-bit loadable, enabled, up/down counter programmed in each LAB.

(5) The t_{LPA} parameter must be added to the t_{LOCAL} parameter for macrocells running in low-power mode.

(6) The t_{ROW}, t_{COL}, and t_{IOC} delays are worst-case values for typical applications. Post-compilation timing simulation or timing analysis is required to determine actual worst-case performance.

Power Consumption

The supply power (P) versus frequency ($\mathbf{f_{MAX}}$) for MAX 9000 devices can be calculated with the following equation:

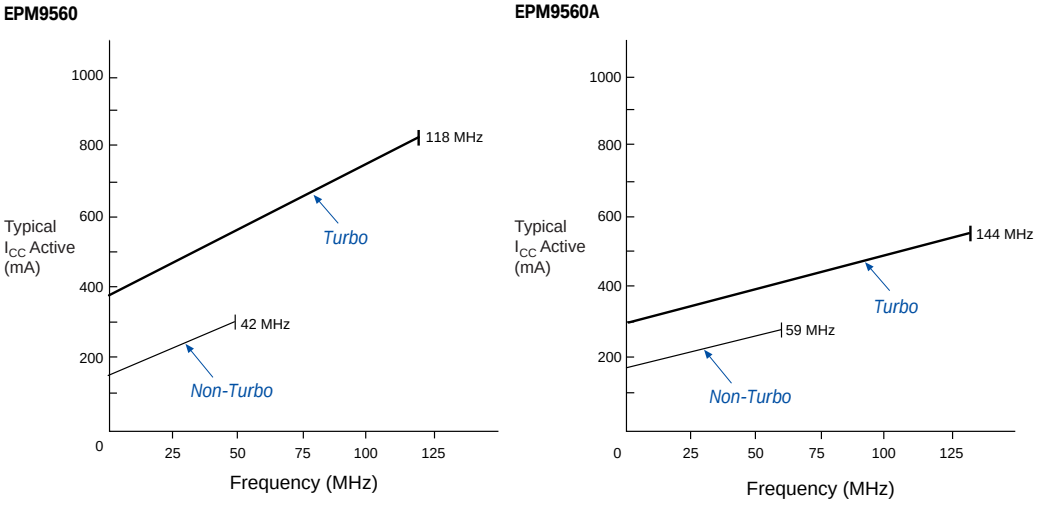
$$P = P_{INT} + P_{IO} = I_{CCINT} \times V_{CC} + P_{IO}$$

The P_{IO} value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in *Application Note 74 (Evaluating Power for Altera Devices)*. The I_{CCINT} value depends on the switching frequency and the application logic.

The I_{CCINT} value is calculated with the following equation:

$$I_{CCINT} = (A \times MC_{TON}) + [B \times (MC_{DEV} - MC_{TON})] + (C \times MC_{USED} \times \mathbf{f_{MAX}} \times \mathbf{tog_{LC}})$$

Figure 15. I_{CC} vs. Frequency for MAX 9000 Devices (Part 2 of 2)



Device Pin-Outs

Tables 26 through 29 show the dedicated pin names and numbers for each EPM9320, EPM9320A, EPM9400, EPM9480, EPM9560, and EPM9560A device package.

Table 26. EPM9320 & EPM9320A Dedicated Pin-Outs (Part 1 of 2) *Note (1)*

Pin Name	84-Pin PLCC *(2)*	208-Pin RQFP	280-Pin PGA *(3)*	356-Pin BGA
DIN1 (GCLK1)	1	182	V10	AD13
DIN2 (GCLK2)	84	183	U10	AF14
DIN3 (GCLR)	13	153	V17	AD1
DIN4 (GOE)	72	4	W2	AC24
TCK	43	78	A9	A18
TMS	55	49	D6	E23
TDI	42	79	C11	A13
TDO	30	108	A18	D3

Notes:
(1) All pins not listed are user I/O pins.
(2) Perform a complete thermal analysis before committing a design to this device package. See *Application Note 74 (Evaluating Power for Altera Devices)*.
(3) EPM9320A devices are not offered in this package.
(4) During in-system programming, each device's VPP pin must be connected to the 5.0-V power supply. During normal device operation, the VPP pin is pulled up internally and can be connected to the 5.0-V supply or left unconnected.
(5) The user I/O pin count includes dedicated input pins and all I/O pins.

Table 27. EPM9400 Dedicated Pin-Outs *Note (1)*

Pin Name	84-Pin PLCC *(2)*	208-Pin RQFP	240-Pin RQFP
DIN1 (GCLK1)	2	182	210
DIN2 (GCLK2)	1	183	211
DIN3 (GCLR)	12	153	187
DIN4 (GOE)	74	4	234
TCK	43	78	91
TMS	54	49	68
TDI	42	79	92
TDO	31	108	114
GND	6, 13, 20, 26, 27, 47, 60, 66, 69, 73	14, 20, 24, 31, 35, 41, 42, 43, 44, 46, 47, 66, 85, 102, 110, 113, 114, 115, 116, 118, 121, 122, 132, 133, 143, 152, 170, 189, 206	5, 14, 25, 34, 45, 54, 65, 66, 81, 96, 110, 115, 126, 127, 146, 147, 166, 167, 186, 200, 216, 229
VCCINT (5.0 V only)	16, 23, 30, 56, 63, 70	10, 19, 30, 45, 112, 128, 139, 148	4, 24, 44, 64, 117, 137, 157, 177
VCCIO (3.3 or 5.0 V)	17, 37, 59, 80	5, 25, 36, 55, 72, 91, 111, 127, 138, 159, 176, 195	15, 35, 55, 73, 86, 101, 116, 136, 156, 176, 192, 205, 220, 235
No Connect (N.C.)	–	6, 7, 8, 9, 11, 12, 13, 109, 144, 145, 146, 147, 149, 150, 151	1, 2, 3, 6, 7, 8, 9, 10, 11, 12, 13, 168, 169, 170, 171, 172, 173, 174, 175, 178, 179, 180, 181, 182, 183, 184, 185, 236, 237, 238, 239, 240
VPP *(3)*	55	48	67
Total User I/O Pins *(4)*	59	139	159

Notes:
(1) All pins not listed are user I/O pins.
(2) Perform a complete thermal analysis before committing a design to this device package. See *Application Note 74 (Evaluating Power for Altera Devices)* for more information.
(3) During in-system programming, each device's VPP pin must be connected to the 5.0-V power supply. During normal device operation, the VPP pin is pulled up internally and can be connected to the 5.0-V supply or left unconnected.
(4) The user I/O pin count includes dedicated input pins and all I/O pins.

Revision History

Information contained in the *MAX 9000 Programmable Logic Device Family Data Sheet* version 6.5 supersedes information published in previous versions.

Version 6.5

Version 6.6 of the *MAX 9000 Programmable Logic Device Family Data Sheet* contains the following change:

- Added Tables 7 through 9.
- Added "Programming Sequence" on page 20 and "Programming Times" on page 20

Version 6.4

Version 6.4 of the *MAX 9000 Programmable Logic Device Family Data Sheet* contains the following change: Updated text on page 23.

Version 6.3

Version 6.3 of the *MAX 9000 Programmable Logic Device Family Data Sheet* contains the following change: added Note (7) to Table 16.

101 Innovation Drive
San Jose, CA 95134
(408) 544-7000
http://www.altera.com
Applications Hotline:
(800) 800-EPLD
Customer Marketing:
(408) 544-7104
Literature Services:
lit_req@altera.com